L Number	Hits		DB	Time stamp
1	8	Torr and Ampere and (electron with (beam and diameter)) and keV	USPAT;	2004/06/14 11:40
			US-PGPUB;	
			EPO; JPO;	
		*	DERWENT;	
		om 14 1/1 11/1 11: \\\\\\\\\\\\\\\\\\\\\\\\\\	IBM_TDB	2004/07/4444
3	3	(Torr and Ampere and (electron with (beam and diameter)) and keV) and (wafer	USPAT;	2004/06/14 11:36
		or substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		T 14	IBM_TDB USPAT;	2004/06/14 12:07
	. 30	Torr and Ampere and (electron with beam) and (beam with diameter) and keV	US-PGPUB;	2004/00/14 12:0/
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
4	8	(Torr and Ampere and (electron with beam) and (beam with diameter) and keV)	USPĀT;	2004/06/14 11:55
7	0	and (wafer or substrate)	US-PGPUB;	2004/00/14 11:55
		and (water or substrate)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	22	(Torr and Ampere and (electron with beam) and (beam with diameter) and keV)	USPĀT;	2004/06/14 11:55
,		not ((Torr and Ampere and (electron with beam) and (beam with diameter) and	US-PGPUB;	2001/00/11/11/55
		keV) and (wafer or substrate))	EPO; JPO;	
		the ty and (which or substitute))	DERWENT;	
			IBM_TDB	
6	40	Torr and Amp and (electron with beam) and (beam with diameter) and keV	USPĀT;	2004/06/14 12:07
ŭ		1011 mile 1 mile (coconed with control with control with the control with	US-PGPUB;	200 11 201 21 12101
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	40	(Torr and Amp and (electron with beam) and (beam with diameter) and keV) not	USPĀT;	2004/06/14 11:58
		((Torr and Ampere and (electron with beam) and (beam with diameter) and keV)	US-PGPUB;	
		not ((Torr and Ampere and (electron with beam) and (beam with diameter) and	EPO; JPO;	
		keV) and (wafer or substrate)))	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM TDB	
8 .	80	Torr and Amp and (electron adj1 beam) and (beam with diameter) and (wafer or	USPĀT;	2004/06/14 12:37
		substrate)	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	45	(Torr and Amp and (electron adj1 beam) and (beam with diameter) and (wafer or	USPAT;	2004/06/14 12:10
		substrate)) not ((Torr and Amp and (electron with beam) and (beam with	US-PGPUB;	
		diameter) and keV) not ((Torr and Ampere and (electron with beam) and (beam	EPO; JPO;	
		with diameter) and keV) not ((Torr and Ampere and (electron with beam) and	DERWENT;	
	_	(beam with diameter) and keV) and (wafer or substrate))))	IBM_TDB	
10	0	Torr and ??nA and (electron adj1 beam) and (beam with (diameter and ???nm))	USPAT;	2004/06/14 12:39
		and ?eV and (wafer or substrate)	US-PGPUB;	
			EPO; JPO;	
		*	DERWENT;	•
	_	T122 A1 (-1 P11	IBM_TDB	2004/04/44 42 26
11	0	Tor and ??nA and (electron adj1 beam) and (beam with (diameter and ???nm))	USPAT;	2004/06/14 12:39
11		and ?eV and (wafer or substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0	To and in A and (alastron add hearn) and (hearn with (diameter and hearn) and	DERWENT; IBM_TDB	2004/04/14 12:4/
12	0	Tor and ?nA and (electron adj1 beam) and (beam with (diameter and ?nm)) and	DERWENT; IBM TDB USPĀT;	2004/06/14 12:40
	o	Tor and ?nA and (electron adj1 beam) and (beam with (diameter and ?nm)) and ?eV and (wafer or substrate)	DERWENT; IBM TDB USPĀT; US-PGPUB;	2004/06/14 12:40
	0		DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO;	2004/06/14 12:40
	0		DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/14 12:40
12		?eV and (wafer or substrate)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
12	33	?eV and (wafer or substrate) torr and nA and (electron adj1 beam) and (beam with (diameter and nm)) and eV	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	
12		?eV and (wafer or substrate)	DERWENT; IBM_TIDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TIDB USPAT; US-PGPUB;	
		?eV and (wafer or substrate) torr and nA and (electron adj1 beam) and (beam with (diameter and nm)) and eV	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/06/14 12:40 2004/06/14 12:41

14	30	(torr and nA and (electron adj1 beam) and (beam with (diameter and nm)) and	USPAT; .	2004/06/14 13:08
	ł	eV and (wafer or substrate)) not ((Torr and Amp and (electron adj1 beam) and	US-PGPUB;	
		(beam with diameter) and (wafer or substrate)) not ((Torr and Amp and (electron	EPO; JPO;	
		with beam) and (beam with diameter) and keV) not ((Torr and Ampere and	DERWENT;	
		(electron with beam) and (beam with diameter) and keV) not ((Torr and Ampere	IBM TDB	
		and (electron with beam) and (beam with diameter) and keV) and (wafer or	_	
		substrate)))))		
15	94	118/\$.ccls. and (nozzle adj1 angle)	USPAT;	2004/06/14 13:16
			US-PGPUB;	
			EPO, JPO.	
			DERWENT;	
	l		IBM TDB	
16	2	6,042,738.pn.	USPĀT;	2004/06/14 13:22
	ì		US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
17	• 4	(("6420701") or ("6042738") or ("5876504") or ("6042738") or ("5684360") or ("6042738")).PN.	USPĀT	2004/06/14 13:22